

TLP3052A, TLP3052AF

1. Applications

- Solid-State Relays
- Triac Drivers
- Home Electric Appliances
- Office Equipment

2. General

The TLP3052A consists of a non zero crossing photo triac, optically coupled to a gallium arsenide infrared emitting diode. The TLP3052A is housed in the DIP6 package and guarantees insulation thickness of 0.4 mm (min). Therefore, the TLP3052A meets the reinforced insulation class requirements of international safety standards.

3. Features

- (1) Peak off-state voltage: 600 V (min)
- (2) Non zero crossing functionary (NZC)
- (3) Trigger LED current: 10 mA (max)
- (4) On-state current: 100 mA (max)
- (5) Isolation voltage: 5000 Vrms (min)
- (6) Safety standards

UL-approved: UL1577 File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

CQC-approved: GB4943.1, GB8898

VDE: Option (D4) EN60747-5-5 (**Note**), pending approval

Maximum operating insulation voltage: 890 Vpeak / 1140 Vpeak (**Note 1**)

Highest permissible overvoltage: 8000 Vpeak

Note: When an EN60747-5-5 approved type is needed, please designate the **Option (D4)**.

Note 1: When maximum operating insulation voltage 1140 Vpeak is needed, please designate the **TLP3052AF**.

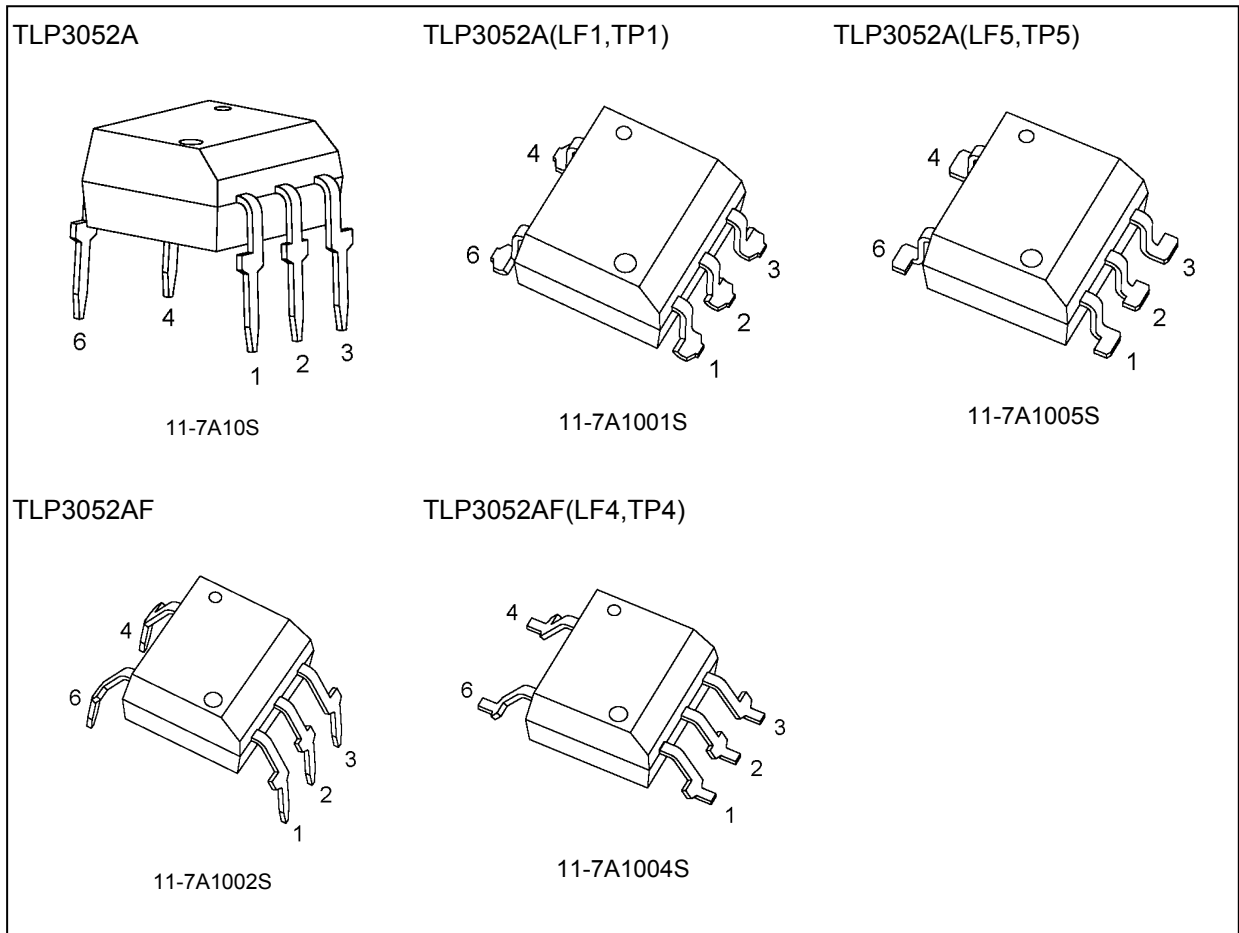
Table 3.1 Mechanical Parameters

Characteristics	7.62 mm Pitch TLP3052A	10.16 mm Pitch TLP3052AF	Unit
Creepage distances	7.0 (min)	8.0 (min)	mm
Clearance distances	7.0 (min)	8.0 (min)	
Internal isolation thickness	0.4 (min)	0.4 (min)	

Start of commercial production

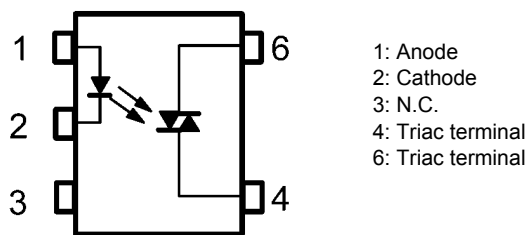
2015-08

4. Packaging (Note)



Note: Through hole type: TLP3052A, TLP3052AF
 Lead forming option: (LF1), (LF4), (LF5)
 Taping option: (TP1), (TP4), (TP5)

5. Pin Assignment



- 1: Anode
- 2: Cathode
- 3: N.C.
- 4: Triac terminal
- 6: Triac terminal

6. Product Naming Conventions (Note)

Type of package used for shipment is denoted by a symbol suffix after a part number. The method of classification is as below.

Example) TLP3052A(TP1,F(O

Part number: TLP3052A

Tape type: TP1 (**Note 1**)

[[G]]/RoHS COMPATIBLE: F (**Note**)

Domestic ID (Country/Region of origin: Japan): (O

Note 1: At the part of tape type, below options are used including lead forming type.

TLP3052A: LF1, TP1, LF5, TP5

TLP3052AF: LF4, TP4

Note: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

7. Absolute Maximum Ratings (Note) (Unless otherwise specified, $T_a = 25\text{ °C}$)

	Characteristics	Symbol	Note	Rating	Unit	
LED	Input forward current	I_F		50	mA	
	Input forward current derating ($T_a \geq 53\text{ °C}$)	$\Delta I_F/\Delta T_a$		-0.7	mA/°C	
	Input forward current (pulsed)	I_{FP}	(Note 1)	1	A	
	Input reverse voltage	V_R		5	V	
	Junction temperature	T_j		125	°C	
	Input power dissipation	P_D		100	mW	
	Input power dissipation derating	$\Delta P_D/\Delta T_a$		-1.0	mW/°C	
Detector	Off-state output terminal voltage	V_{DRM}		600	V	
	R.M.S. on-state current	$I_{T(RMS)}$		($T_a = 25\text{ °C}$)	100	mA
				($T_a = 70\text{ °C}$)	50	mA
	R.M.S. on-state current derating ($T_a \geq 25\text{ °C}$)	$\Delta I_{T(RMS)}/\Delta T_a$		-1.1	mA/°C	
	ON-state current (pulsed)	I_{ONP}	(Note 2)	2	A	
	Peak non-repetitive surge current	I_{TSM}	(Note 3)	1.2	A	
	Junction temperature	T_j		125	°C	
	Output power dissipation	P_O		300	mW	
	Output power dissipation derating ($T_a \geq 25\text{ °C}$)	$\Delta P_O/\Delta T_a$		-4.0	mW/°C	
Common	Total power dissipation	P_T		400	mW	
	Total power dissipation derating ($T_a \geq 25\text{ °C}$)	$\Delta P_T/\Delta T_a$		-4.4	mW/°C	
	Operating temperature	T_{opr}		-40 to 100	°C	
	Storage temperature	T_{stg}		-55 to 125	°C	
	Lead soldering temperature (10 s)	T_{sol}		260	°C	
	Isolation voltage AC, 60 s, R.H. $\leq 60\%$	BV_S	(Note 4)	5000	Vrms	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) $\leq 100\text{ }\mu\text{s}$, 100 pps

Note 2: Pulse width (PW) $\leq 100\text{ }\mu\text{s}$, 120 pps

Note 3: Pulse width (PW) $\leq 10\text{ ms}$

Note 4: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4 and 6 are shorted together.

8. Recommended Operating Conditions (Note)

Characteristics	Symbol	Note	Min	Typ.	Max	Unit
AC mains voltage	V_{AC}	(Note 1)	—	—	240	V
Input forward current	I_F		15	20	25	mA
ON-state current (pulsed)	I_{ONP}		—	—	1	A
Operating temperature	T_{opr}		-25	—	85	°C

Note: The recommended operating conditions are given as a design guide necessary to obtain the intended performance of the device. Each parameter is an independent value. When creating a system design using this device, the electrical characteristics specified in this datasheet should also be considered.

Note 1: AC use only.

9. Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V_F		$I_F = 10\text{ mA}$	1.0	1.15	1.3	V
	Input reverse current	I_R		$V_R = 5\text{ V}$	—	—	10	μA
	Input capacitance	C_t		$V = 0\text{ V}, f = 1\text{ MHz}$	—	30	—	pF
Detector	Peak off-state current	I_{DRM}		$V_{DRM} = 600\text{ V}$	—	10	1000	nA
	Peak on-state voltage	V_{TM}		$I_{TM} = 100\text{ mA}$	—	1.7	3.0	V
	Holding current	I_H		—	—	0.6	—	mA
	Critical rate of rise of off-state voltage	dv/dt		$V_{in} = 240\text{ V}, T_a = 25\text{ }^\circ\text{C}$ See Fig. 9.1	—	2000	—	$\text{V}/\mu\text{s}$
	Critical rate of rise of commutating voltage (dv/dt)	dv/dt(c)		$V_{in} = 60\text{ Vrms}, I_T = 15\text{ mA}$ See Fig. 9.1	—	0.2	—	

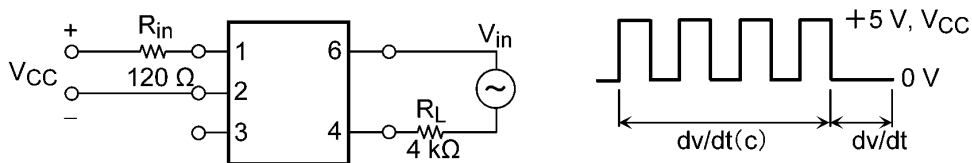


Fig. 9.1 dv/dt Test Circuit

10. Coupled Electrical Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Trigger LED current	I_{FT}		$V_T = 6\text{ V}$	—	—	10	mA

11. Isolation Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C_S	(Note 1)	$V_S = 0\text{ V}, f = 1\text{ MHz}$	—	0.8	—	pF
Isolation resistance	R_S	(Note 1)	$V_S = 500\text{ V}, \text{R.H.} \leq 60\%$	1×10^{12}	10^{14}	—	Ω
Isolation voltage	BV_S	(Note 1)	AC, 60 s	5000	—	—	Vrms
			AC, 1 s in oil	—	10000	—	
			DC, 60 s in oil	—	10000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1, 2 and 3 are shorted together, and pins 4 and 6 are shorted together.

12. Characteristics Curves (Note)

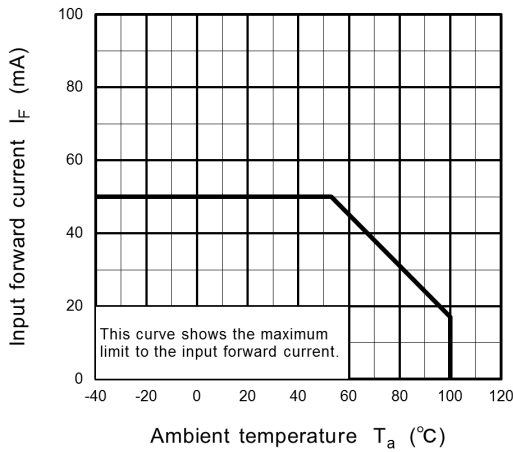


Fig. 12.1 $I_F - T_a$

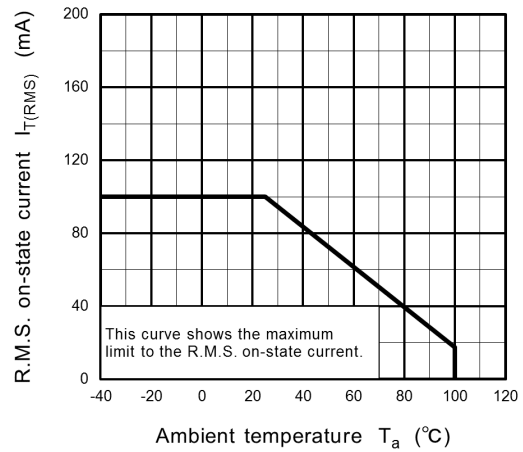


Fig. 12.2 $I_{T(RMS)} - T_a$

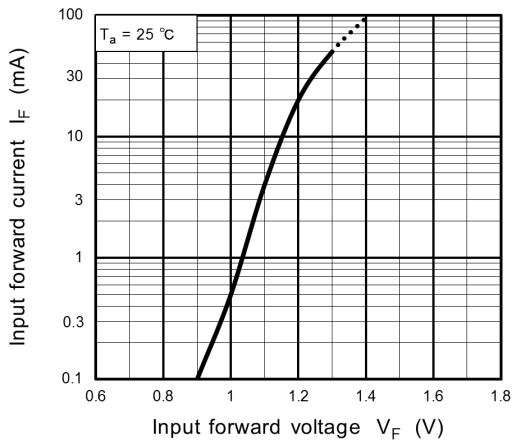


Fig. 12.3 $I_F - V_F$

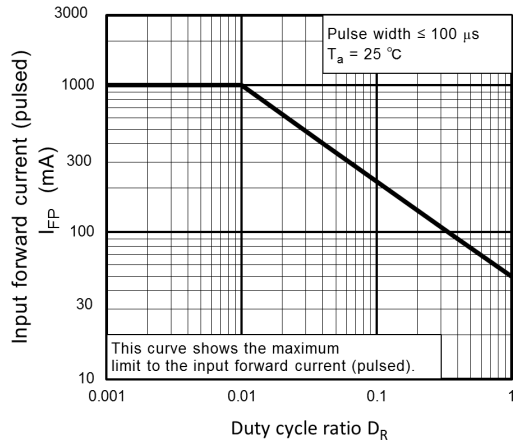


Fig. 12.4 $I_{FP} - D_R$

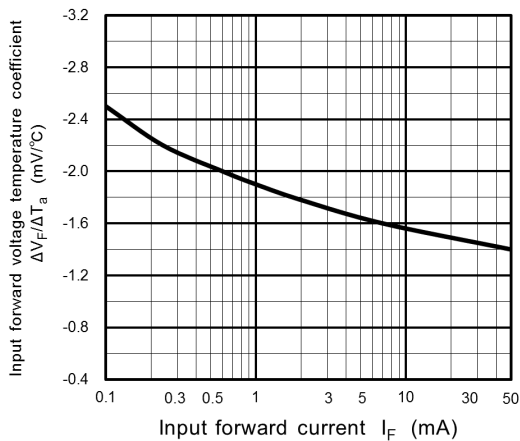


Fig. 12.5 $\Delta V_F/\Delta T_a - I_F$

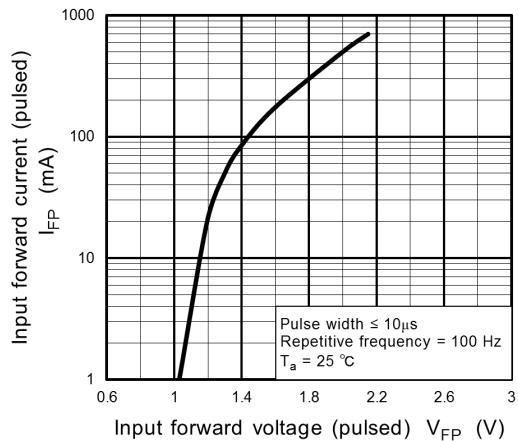


Fig. 12.6 $I_{FP} - V_{FP}$

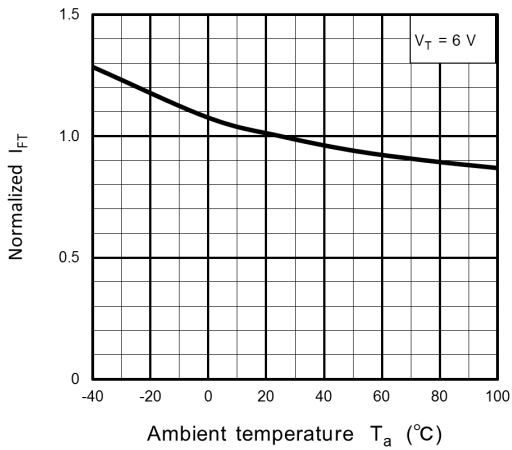


Fig. 12.7 Normalized I_{FT} - T_a

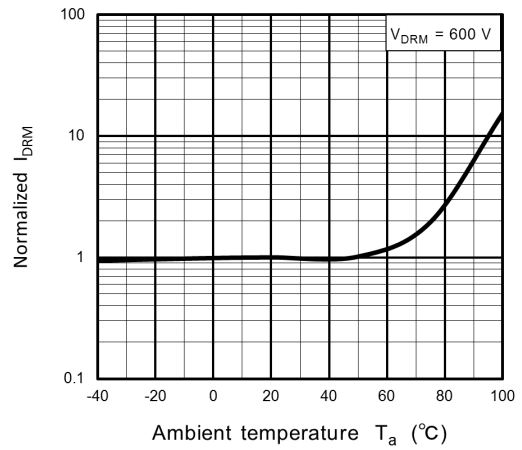


Fig. 12.8 Normalized I_{DRM} - T_a

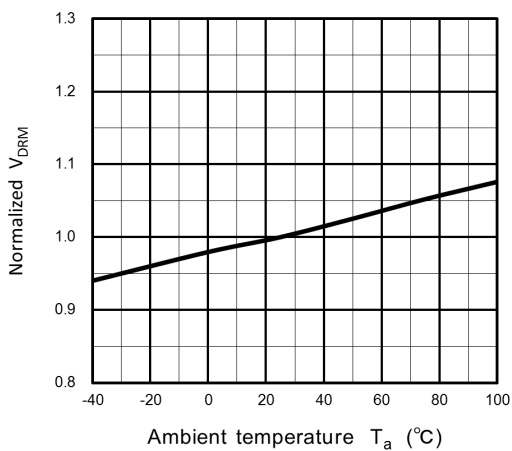


Fig. 12.9 Normalized V_{DRM} - T_a

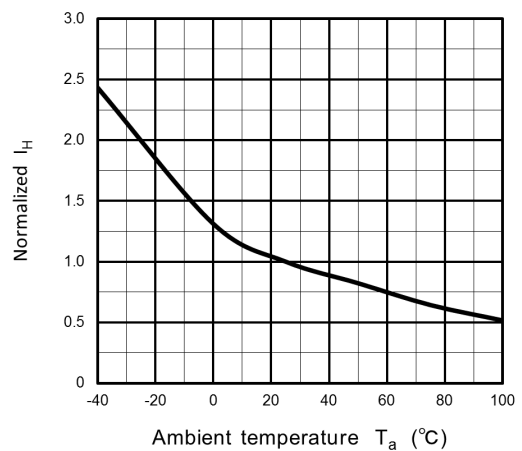


Fig. 12.10 Normalized I_H - T_a

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

13. Soldering and Storage

13.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

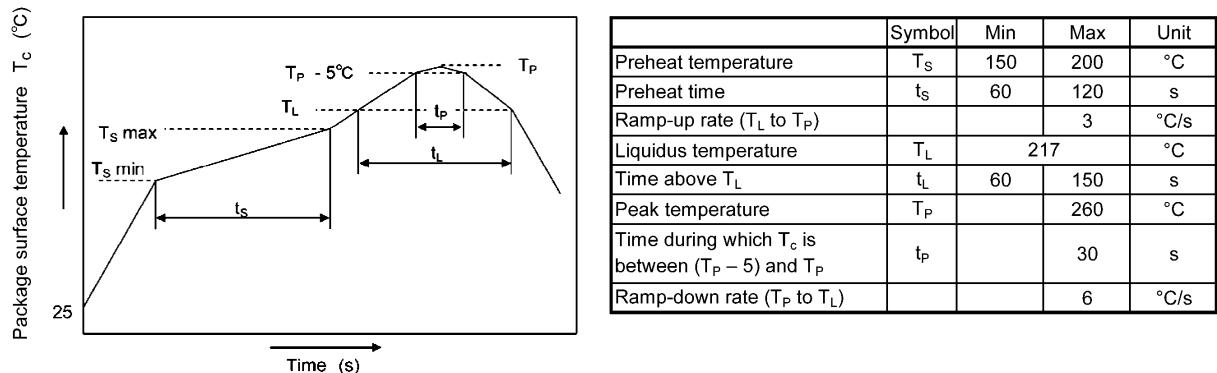


Fig. 13.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

- When using soldering flow
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
Mounting condition of 260 °C within 10 seconds is recommended.
Flow soldering must be performed once.
- When using soldering Iron
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
Heating by soldering iron must be done only once per lead.

13.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45% to 75%, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

14. Land Pattern Dimensions (for reference only)

(Unit: mm)

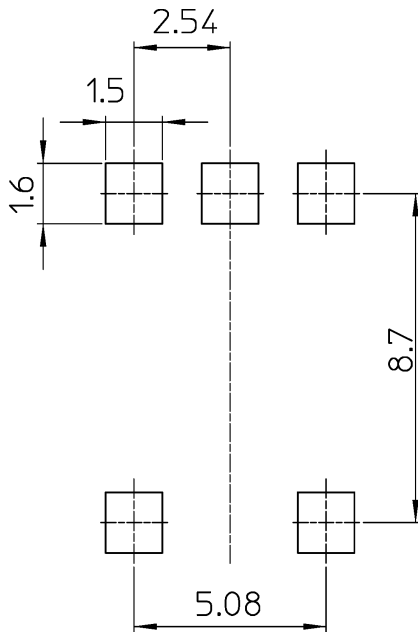


Fig. 14.1 TLP3052A
Lead forming and taping option
(LF1), (TP1), (LF5), (TP5)

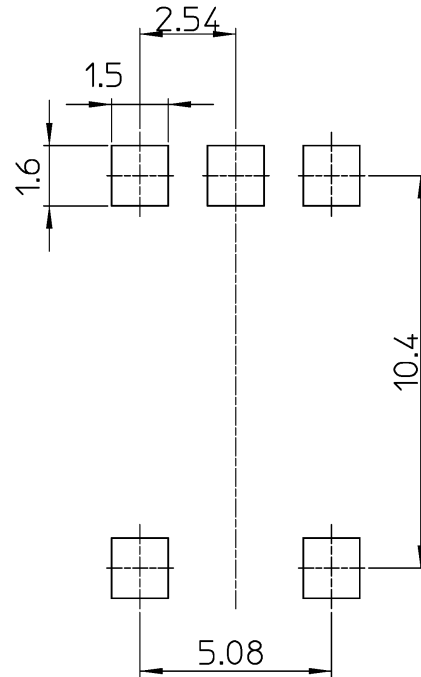


Fig. 14.2 TLP3052AF
Lead forming and taping option
(LF4), (TP4)

15. Marking (Note)

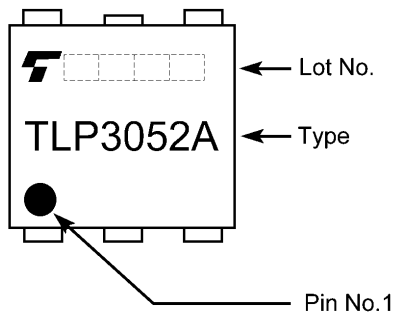


Fig. 15.1 TLP3052A

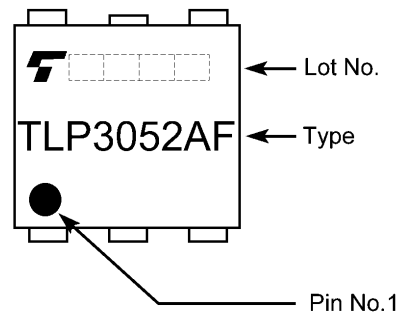


Fig. 15.2 TLP3052AF

Note: A different marking is used for photocouplers that have been qualified according to option (D4) of EN60747. See Fig.16.3 and Fig.16.4.

16. EN60747-5-5 Option (D4) Specification

- Part number: TLP3052A (Note)
- The following part naming conventions are used for the devices that have been qualified according to option (D4) of EN60747.
 Example: TLP3052A(D4-TP1,F(O)
 D4: EN60747 option
 TP1: Tape type
 F: [[G]]/RoHS COMPATIBLE (Note 1)
 (O: Domestic ID (Country/Region of origin: Japan)

Note: Use TOSHIBA standard type number for safety standard application.
 e.g., TLP3052A(D4) → TLP3052A

Note 1: Please contact your Toshiba sales representative for details on environmental information such as the product's RoHS compatibility.

RoHS is the Directive 2011/65/EU of the European Parliament and of the Council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronics equipment.

Description		Symbol	Rating	Unit
Application classification				
for rated mains voltage ≤ 300 Vrms			I-IV	—
for rated mains voltage ≤ 600 Vrms			I-III	
Climatic classification			40 / 100 / 21	—
Pollution degree			2	—
Maximum operating insulation voltage	TLPxxxx type	V _{IORM}	890	V _{peak}
	TLPxxxxF type		1140	
Input to output test voltage, Method A V _{pr} = 1.6 × V _{IORM} , type and sample test t _p = 10 s, partial discharge < 5 pC	TLPxxxx type	V _{pr}	1424	V _{peak}
	TLPxxxxF type		1824	
Input to output test voltage, Method B V _{pr} = 1.875 × V _{IORM} , 100 % production test t _p = 1 s, partial discharge < 5 pC	TLPxxxx type	V _{pr}	1670	V _{peak}
	TLPxxxxF type		2140	
Highest permissible overvoltage (transient overvoltage, t _{pr} = 60 s)		V _{TR}	8000	V _{peak}
Safety limiting values (max. permissible ratings in case of fault, also refer to thermal derating curve)				
current (input current I _F , P _{so} = 0)		I _{si}	400	mA
power (output or total power dissipation)		P _{so}	700	mW
temperature		T _{si}	150	°C
Insulation resistance	V _{IO} = 500 V, T _a = 25 °C V _{IO} = 500 V, T _a = 100 °C V _{IO} = 500 V, T _a = T _{si}	R _{si}	≥ 10 ¹² ≥ 10 ¹¹ ≥ 10 ⁹	Ω

Fig. 16.1 EN60747 Insulation Characteristics

Table 16.1 Insulation Related Specifications (Note)

Insulation Related Parameters	Symbol	TLP3052A	TLP3052AF
Minimum creepage distance	Cr	7.0 mm	8.0 mm
Minimum clearance	Cl	7.0 mm	8.0 mm
Minimum insulation thickness	ti	0.4 mm	0.4 mm
Comparative tracking index	CTI	175	175

Note: If a printed circuit is incorporated, the creepage distance and clearance may be reduced below this value. (e.g., at a standard distance between soldering eye centers of 7.5 mm). If this is not permissible, the user shall take suitable measures.

Note: This photocoupler is suitable for **safe electrical isolation** only within the safety limit data. Maintenance of the safety data shall be ensured by means of protective circuits.



Fig. 16.2 Marking on packing for EN60747

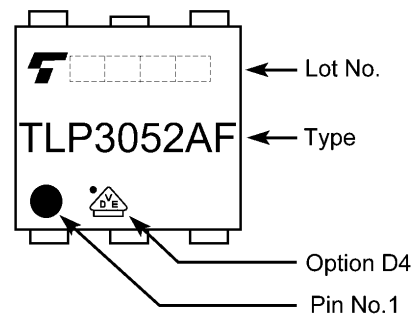
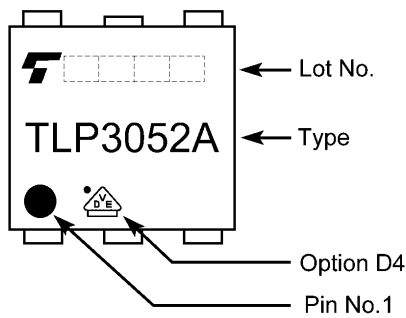


Fig. 16.3 Marking Example of TLP3052A (Note) Fig. 16.4 Marking Example of TLP3052AF (Note)

Note: The above marking is applied to the photocouplers that have been qualified according to option (D4) of EN60747.

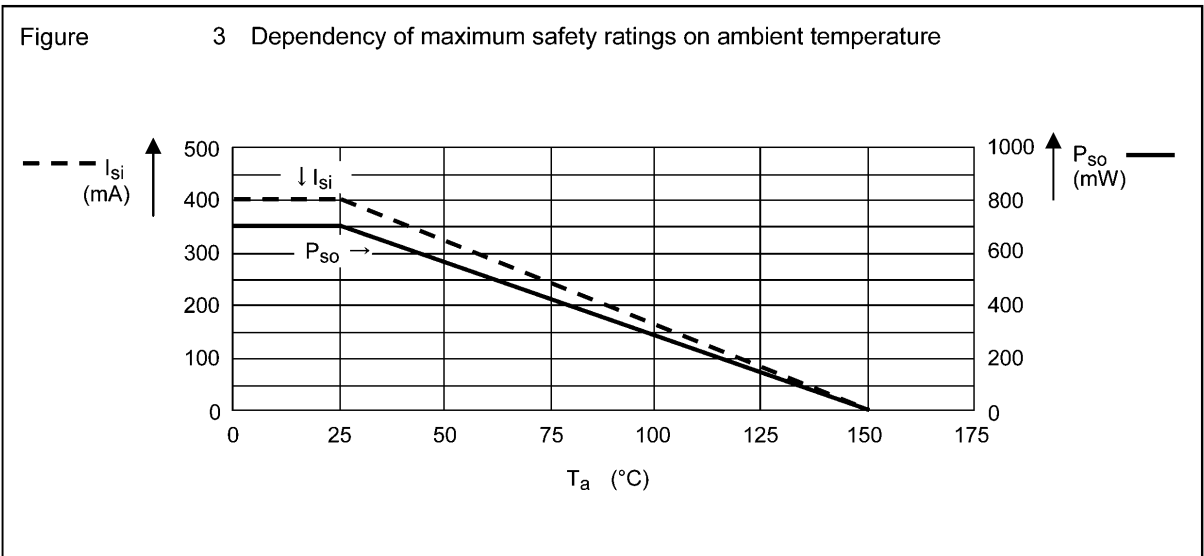
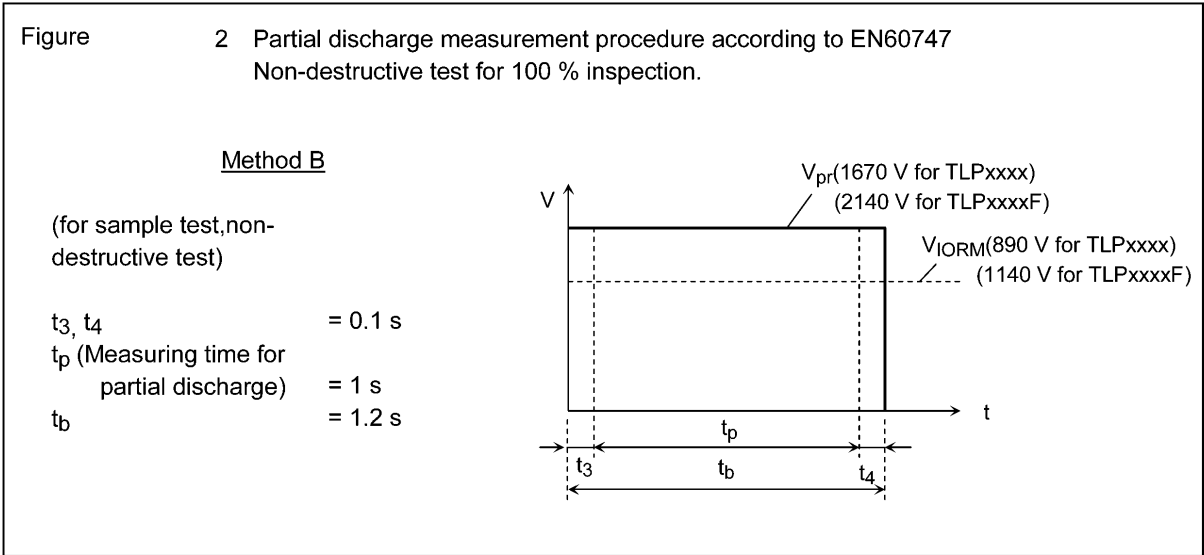
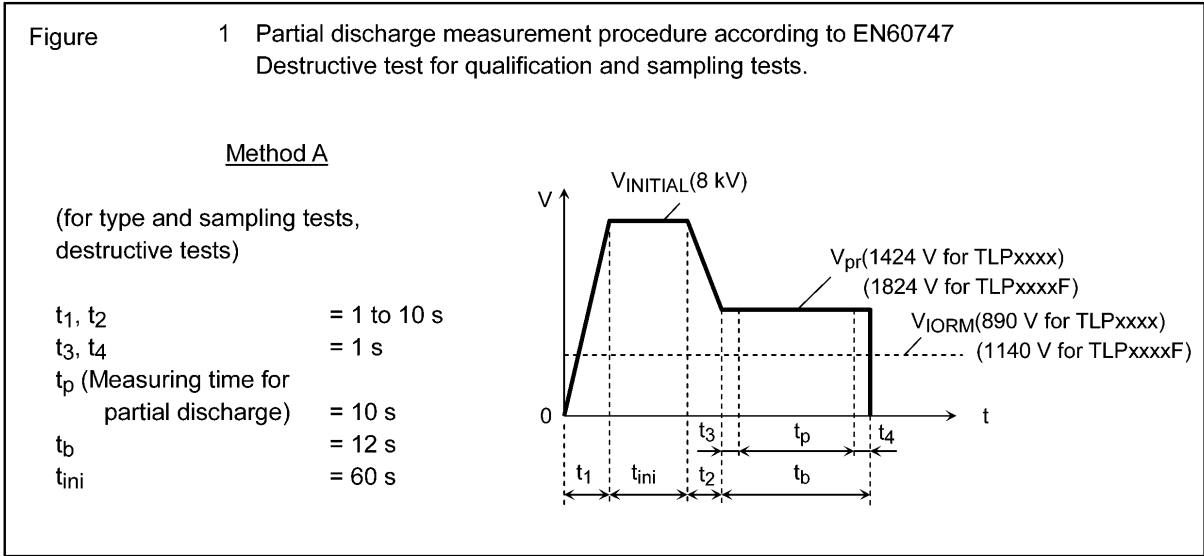
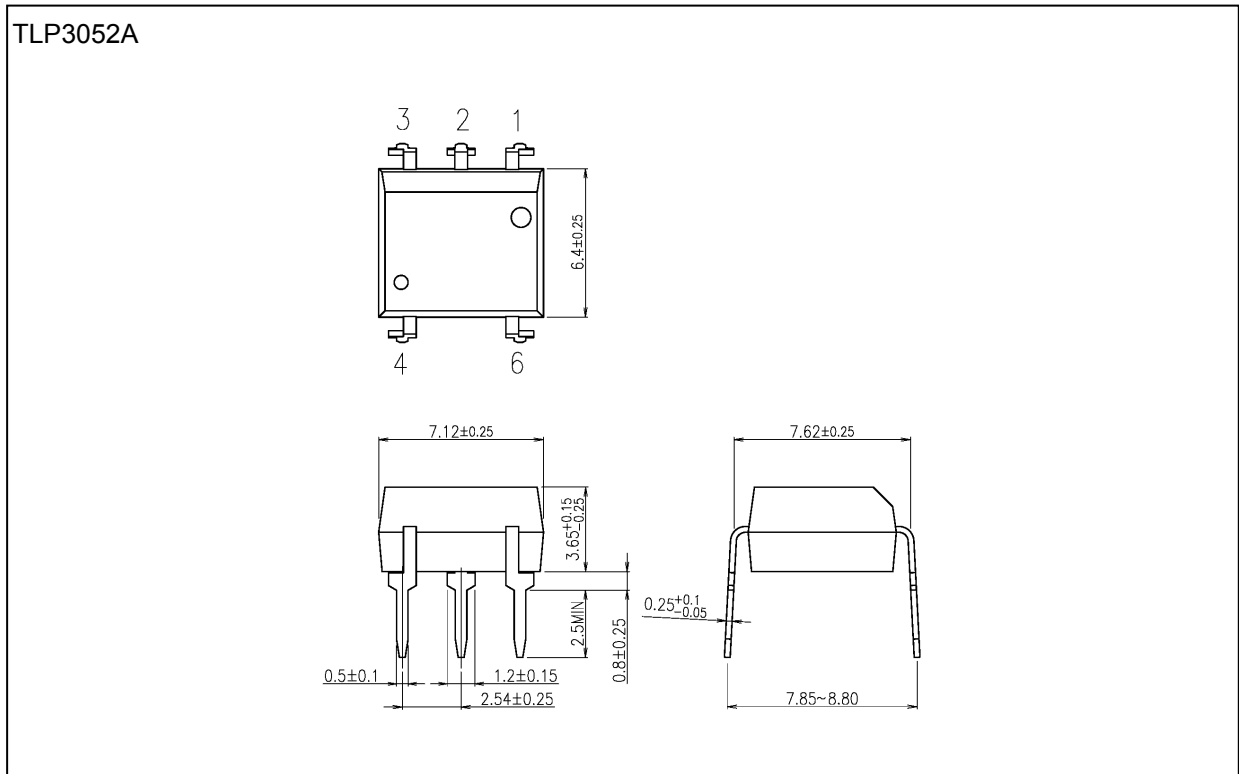


Fig. 16.5 Measurement Procedure

Package Dimensions

Unit: mm

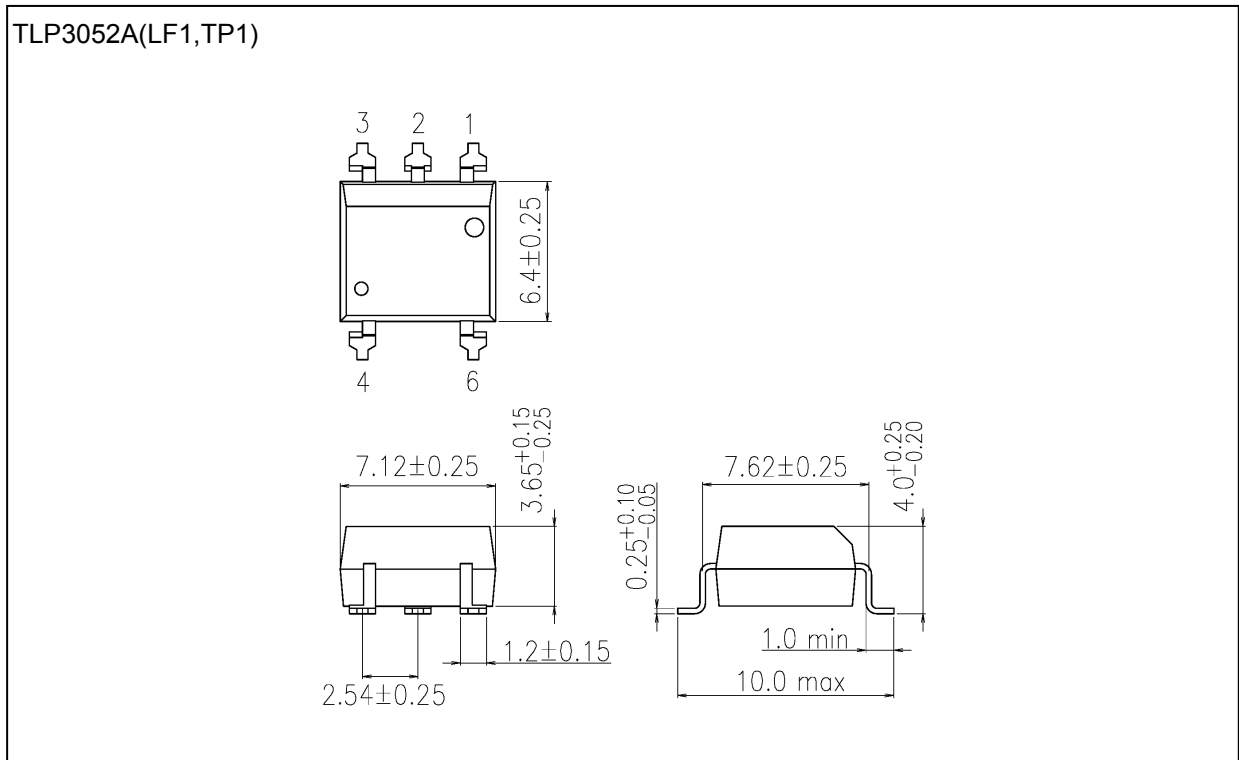


Weight: 0.40 g (typ.)

Package Name(s)
TOSHIBA: 11-7A10S

Package Dimensions

Unit: mm

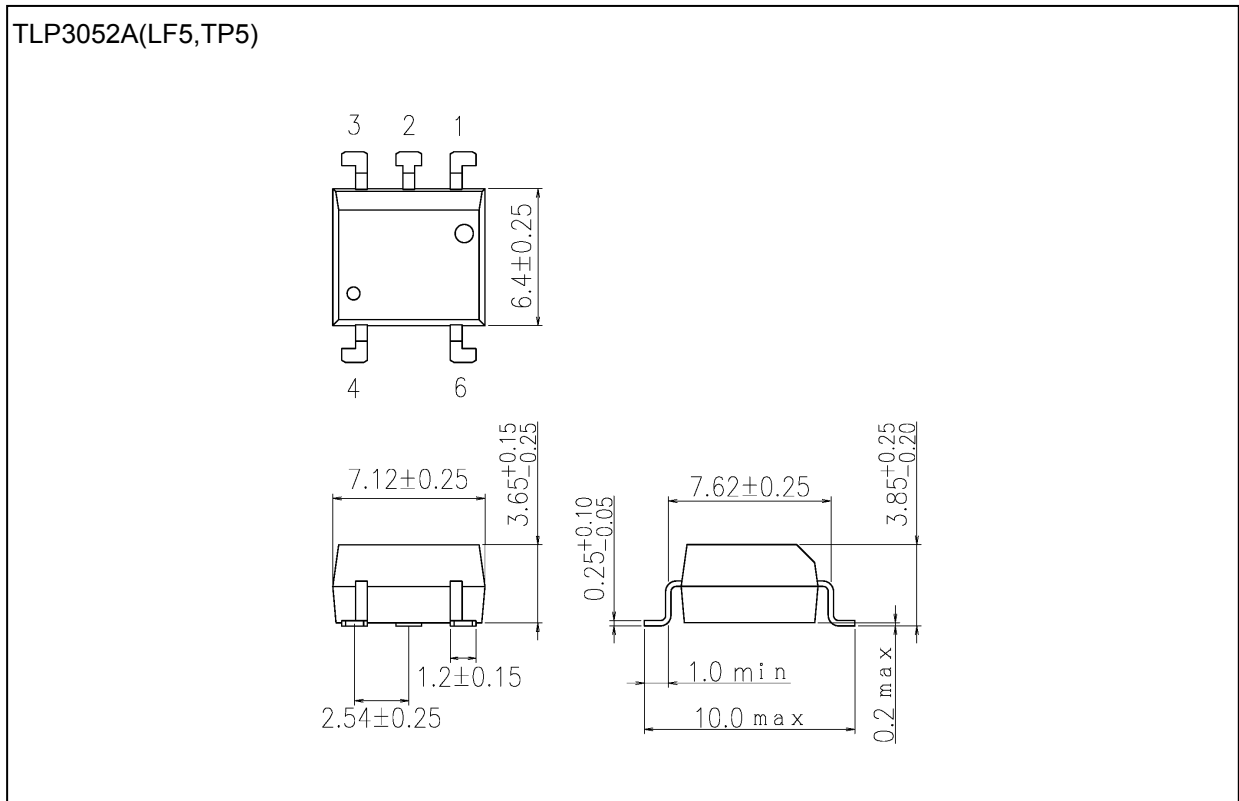


Weight: 0.39 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1001S

Package Dimensions

Unit: mm

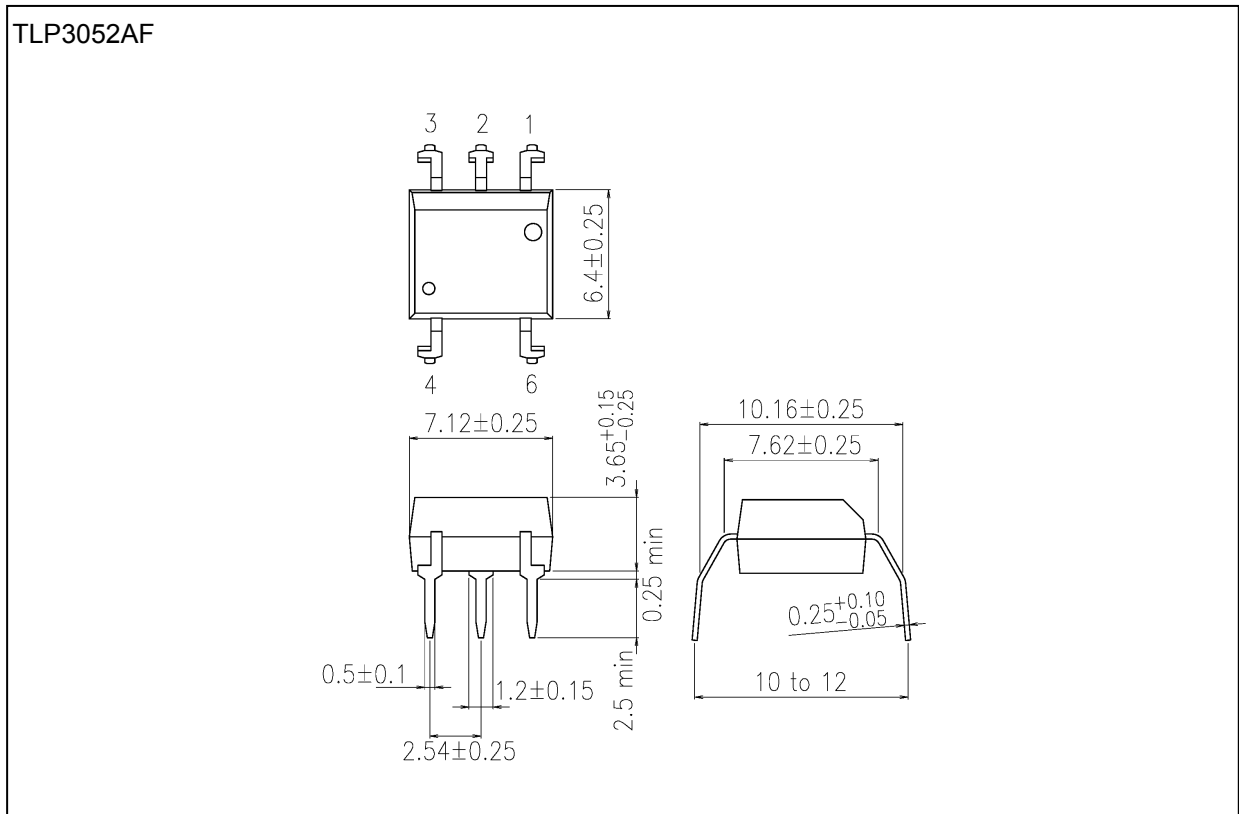


Weight: 0.39 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1005S

Package Dimensions

Unit: mm

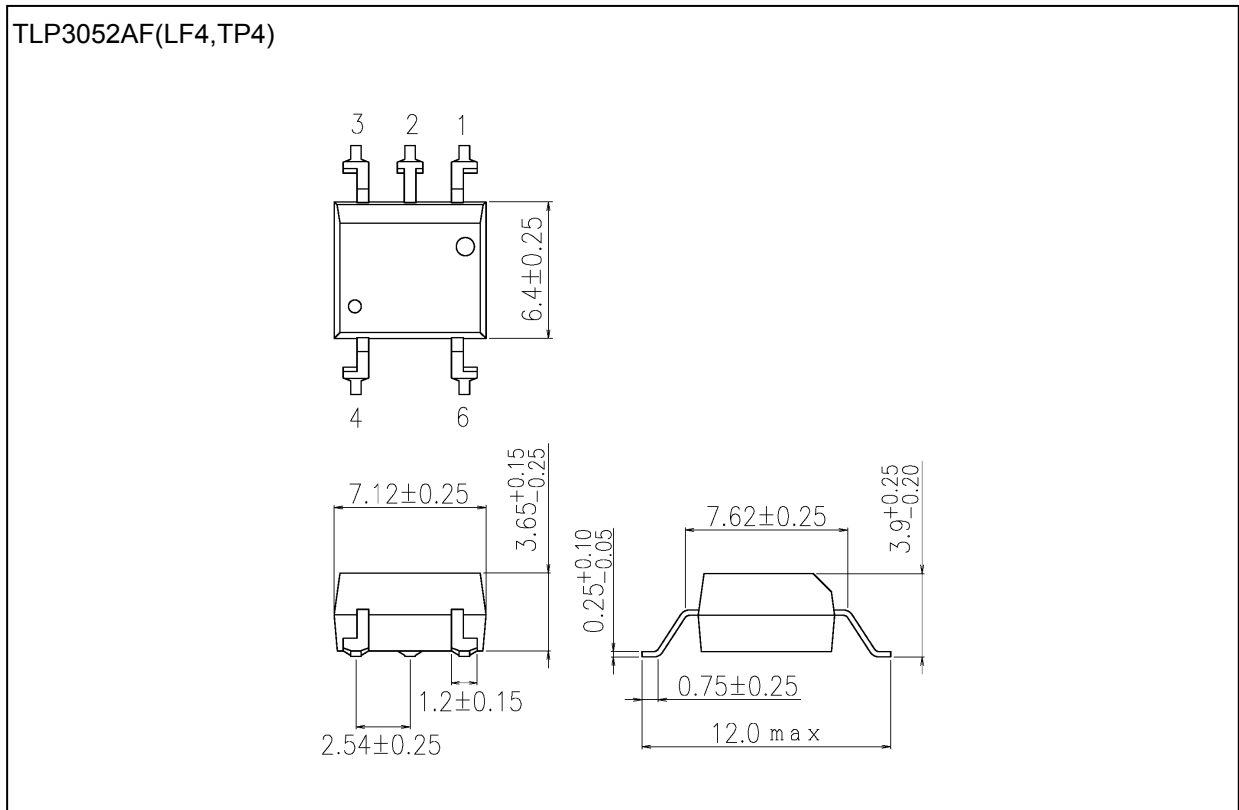


Weight: 0.40 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1002S

Package Dimensions

Unit: mm



Weight: 0.39 g (typ.)

Package Name(s)
TOSHIBA: 11-7A1004S

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